

EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -
Wholesale and Retail.

Avalanche Stud Thyristor Type STA32-250-12

Optimum power handling / Low on-state and switching losses
 Designed for traction and industrial applications

Mean on-state current	I _{TAV}	250 A					
Repetitive peak off-state voltage	V _{DRM}	600÷1200 V					
Repetitive peak reverse voltage	V _{RRM}						
Turn-off time	t _q	160 µs					
V _{DRM} , V _{RRM} , V	600	700	800	900	1000	1100	1200
Voltage code	6	7	8	9	10	11	12
T _j , °C				-60÷140			

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	250 294	T _c = 107 °C; T _c = 100 °C; 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	393	T _c = 100 °C; 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	8.0 9.0	T _j =T _j _{max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			8.5 10.0	T _j =T _j _{max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² s·10 ³	320 400	T _j =T _j _{max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			290 410	T _j =T _j _{max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	600÷1200	T _{j min} < T _j <T _j _{max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	700÷1300	T _{j min} < T _j <T _j _{max} ; 180° half-sine wave; single pulse; Gate open	
V _(BR)	Breakdown voltage	V	850÷1700	T _{j min} < T _j <T _j _{max} ; I _{RRM} = 100 mA; 180° half-sine wave; single pulse; Gate open	

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V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6 \cdot V_{DRM}$ $0.6 \cdot V_{RRM}$	$T_j = T_{j\max}$; Gate open
P_{RSM}	Surge reverse power dissipation	kW	16	$T_j = T_{j\max}$; $t_p = 100 \mu s$; 180° half-sine wave; single pulse
TRIGGERING				
I_{FGM}	Peak forward gate current	A	6	$T_j = T_{j\max}$
V_{RGM}	Peak reverse gate voltage	V	5	$T_j = T_{j\max}$
P_G	Gate power dissipation	W	3	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μs	800	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 3000$ A; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu s$; $di_G/dt \geq 2$ A/ μs
THERMAL				
T_{stg}	Storage temperature	°C	-60÷50	
T_j	Operating junction temperature	°C	-60÷140	
MECHANICAL				
M	Tightening torque	Nm	25÷35	
a	Acceleration	m/s ²	100	

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V_{TM}	Peak on-state voltage, max	V	1.60	$T_j = 25$ °C; $I_{TM} = 785$ A
$V_{T(TO)}$	On-state threshold voltage, max	V	1.045	$T_j = T_{j\max}$;
r_T	On-state slope resistance, max	$m\Omega$	0.767	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
I_L	Latching current, max	mA	700	$T_j = 25$ °C; $V_D = 12$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu s$; $di_G/dt \geq 1$ A/ μs
I_H	Holding current, max	mA	300	$T_j = 25$ °C; $V_D = 12$ V; Gate open
BLOCKING				
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	35	$T_j = T_{j\max}$; $V_D = V_{DRM}$; $V_R = V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μs	320 500 1000	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; Gate open
TRIGGERING				
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$
I_{GT}	Gate trigger direct current, max	mA	400 250 150	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$
V_{GD}	Gate non-trigger direct voltage, min	V	0.60	$T_j = T_{j\max}$;
I_{GD}	Gate non-trigger direct current, min	mA	30.00	$V_D = 0.67 \cdot V_{DRM}$; Direct gate current
SWITCHING				
t_{gd}	Delay time, max	μs	1.25	$T_j = 25$ °C; $V_D = 600$ V; $I_{TM} = I_{TAV}$; $di/dt = 200$ A/ μs ;
t_{gt}	Turn-on time, max	μs	4.00	Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50 \mu s$; $di_G/dt = 2$ A/ μs
t_q	Turn-off time ²⁾ , max	μs	160	$dv_D/dt = 50$ V/ μs ; $T_j = T_{j\max}$; $I_{TM} = I_{TAV}$; $di_R/dt = -10$ A/ μs ; $V_R = 100$ V; $V_D = 0.67 \cdot V_{DRM}$,
Q_{rr}	Total recovered charge, max	μC	490	$T_j = T_{j\max}$; $I_{TM} = 250$ A;
t_{rr}	Reverse recovery time, max	μs	13.0	

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I _{rrM}	Peak reverse recovery current, max	A	75.0	di _R /dt=-10 A/μs; V _R =100 V
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THERMAL

R _{thjc}	Thermal resistance, junction to case, max	°C/W	0.0850	Direct current
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MECHANICAL

w	Weight, max	g	440	
D _s	Surface creepage distance	mm (inch)	12.4 (4.882)	
D _a	Air strike distance	mm (inch)	12.4 (4.882)	

PART NUMBERING GUIDE

STA	32	320	12	7	3
1	2	3	4	5	6

1. STA - Avalanche Stud Thyristor
2. Element Diameter
3. Mean on-state current, A
4. Voltage code
5. Critical rate of rise of on-state current non-repetitive, V/
μs
6. Turn-off time (dv_D/dt=50 V/μs)

NOTES

1) Critical rate of rise of on-state current non-repetitive

Symbol of Group (dv _D /dt) _{crit} , V/μs	5	6	7
	320	500	1000

2) Turn-off time (dv_D/dt=50 V/μs)

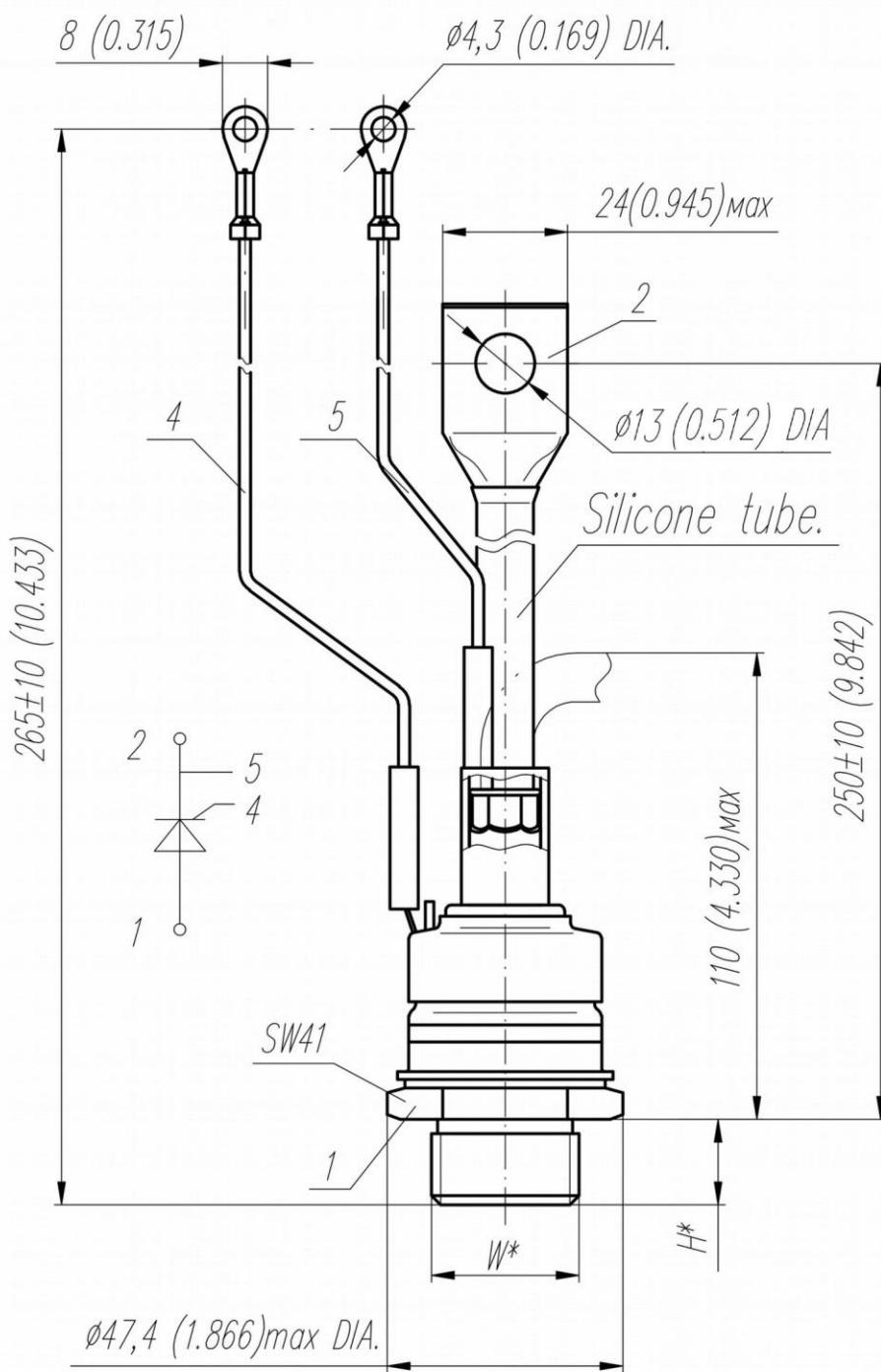
Symbol of Group t _q , μs	3
	160

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OVERALL DIMENSIONS

Package type: T.SB1



Type of screw	W	H
Metric Screw Type C	M24x1,5 – 8g	19
Metric Screw Type B(upon request)	M20x1,5 – 8g	15

Polarity	Example of code designation	Reference designation	Colors		
			Anode	Cathode	Gate
Anode to stud	STA32_27		-	Red tube	White

All dimensions in millimeters (inches)